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ICS 31.030
CCS L90

SJ

INDUSTRY STANDARD OF THE PEOPLE'S REPUBLIC OF CHINA

SJ/T 11390-2019

Test method for lead-free solder

无铅焊料试验方法

(English Translation)

Implemented on: July 1, 2020

Issued by: Ministry of Industry and Information Technology

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1 Foreword

SJ/T 11390-2019 was issued by Ministry of Industry and Information Technology on 24 December 2019 and has been in force since 1 July 2020.

2 Scope

This standard specifies melting temperature, mechanical stretching, spreading, wetting, solder joint stretching and shearing, QFP lead solder joint 45° stretching, chip component solder joint shearing and core tinning for lead-free solders Test method for wire splash.

3 About this standard

Sector: Electronics Industry Standard (Recommended)

Issued by: Ministry of Industry and Information Technology

English translation: about 10 pages (approximate)

Chinese original: about 15,197 characters

4 Classification and status

International classification (ICS): 31.030

Chinese Standard Classification (CCS): L 90

Prefix SJ/T: recommended standard.

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